

REMARKS

Claim 1 stands rejected under 35 U.S.C. §102(b) as being anticipated by United States Patent No. 5,838,412 to Ueda et al. Applicants respectfully traverse this rejection.

Applicants respectfully submit that the Ueda et al. reference fails to disclose the present invention. In particular, the Ueda et al. reference fails to disclose a liquid crystal display unit with first, second and third boards, where "said third board is formed of the same material in the same process as said first board, and is divided from said first board," as defined in Claim 1. One example of an embodiment of the present invention as defined in Claim 1 is shown in Figures 3 and 4, which includes a first board 1 (with signal lines 3, scanning lines 4 and pixel electrodes 23); a second board 5 (with a common electrode 6); and third board 12 (which, in this embodiment, includes signal line driver 9).

As shown in Figure 4, the third board 12 is formed of the same material in the same process as the first board 1, and the third board 12 is divided from the first board 1 by severing along lines 17. One of the advantages of such a configuration is to increase the yield rate of the first board. For example, if all of the circuits of the first and third boards are made on the same board, any error in any of the circuits causes the entire board to be considered as defective. However, if some of the circuits, such as the signal line driver, are made on a separate board (the third board), and if a defect exists on either board, only that board is considered defective, while the other board is acceptable. Such a configuration increases the yield rate of the boards. Moreover, by making the third board of the same material and at the same time as the first board, and simply dividing the third board from the

first board, the boards can be manufactured at a lower cost than if they were made in separate processes.

In contrast, the Ueda et al. reference fails to disclose such a configuration in which the third board is formed of the same material in the same process as the first board, and is divided from the first board, as defined in Claim 1. The Ueda et al. reference does not even mention such features. The Ueda et al. reference even has a different objective than the present invention. Namely, one of the objectives of the Ueda et al. reference is to prevent disconnection of the wiring on the flexible substrate when folding the flexible substrate. Accordingly, as all of the features of Claim 1 are not disclosed or suggested in the Ueda et al. reference, Applicants respectfully request the withdrawal of this §102(b) rejection of Claim 1 under the Ueda et al. reference.

Claims 2-5 stand rejected under 35 U.S.C. § 103 as being unpatentable over Ueda et al. in view of United States Patent No. 5,502,889 to Casson et al. Applicants have cancelled Claim 2, without prejudice, thereby rendering this rejection moot with respect to this claim. However, with respect to Claims 3-5, Applicants respectfully traverse this rejection.

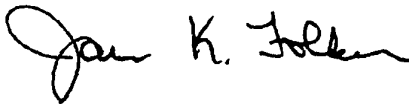
Claims 3-5 all depend from independent Claim 1, and therefore include all of the features of Claim 1, plus additional features. Accordingly, Applicants respectfully request that the §103 rejection of dependent Claims 3-5 under Ueda et al. in view of Casson et al. be withdrawn considering the above remarks directed to independent Claim 1, and also because the Casson et al. reference fails to disclose or suggest the missing features discussed

above. More specifically, the Casson et al. reference fails to disclose such a configuration in which the third board is formed of the same material in the same process as the first board, and is divided from the first board, as defined in Claim 1. Initially, Applicants dispute that Column 5, lines 20-30 of the Casson et al. reference suggests making multiple boards of the same material. This section of Casson et al. states that multiple boards can be stacked, and that those boards are each covered with epoxy and sprinkled with metal particles. However, this section of Casson et al. fails to state that the boards are made of the same material, it only states that they are covered with the same material. Further, this portion of the Casson et al. reference is in the Background section and it relates to a prior art device, and not to the invention of the Casson et al. reference. In fact, the Casson et al. reference states that there are several problems with such a configuration. *See e.g.*, column 5, lines 43 through column 6, lines 13 of Casson et al. Accordingly, Applicants respectfully submit that the Casson et al. reference actually teaches away from using such a configuration. Finally, the object of Casson et al. is to ensure electrical and mechanical connection among a multilayer circuit board, which is different from the object of the present invention. Accordingly, for all of these reasons, Applicants respectfully submit that the present invention would not have resulted from the proposed combination of the Ueda et al. reference and the Casson et al. reference.

For all of the above reasons, Applicants request reconsideration and allowance of the claimed invention. Should the Examiner be of the opinion that a telephone conference would aid in the prosecution of the application, or that outstanding issues exist, the Examiner is invited to contact the undersigned.

Respectfully submitted,

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